

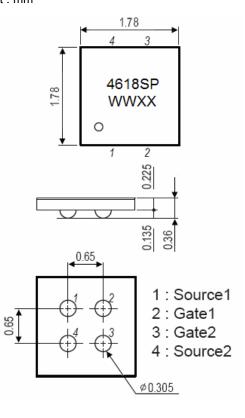
Common-Drain Dual N-Channel Enhancement Mode Field Effect Transistor

Description

The HM4618SP uses advanced trench technology to provide excellent $R_{SS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V while retaining a 12V $V_{GS(MAX)}$ rating. It is ESD protected. This device is suitable for use as a unidirectional or bi-directional load switch, facilitated by its common-drain configuration.

Package Dimensions

Unit : mm

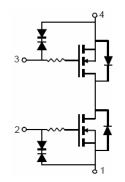


General Features

- V_{SSS} =20V,I_S =6A
- 2.5V drive
- Common-drain type
- 2KV HBM
- Package Information
- Minimum Packing Quantity : 5,000 pcs./reel

Application

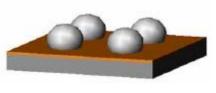
• Lithium-ion battery charging and discharging switch



Equivalent Circuit



Marking and pin assignment



CSP top view

Absolute Maximum Ratings (T_A =25[°]Cunless otherwise noted)

Symbol	Parameter	Limit	Unit	
Vsss	Source to Source Voltage	20	V	
Vgss	Gate-Source Voltage	±12	V	
I _S	Source Current(DC)	6	А	
I _{SP}	Source Current (Pulse)	60	А	
Ρτ	Total Dissipation	1.6	W	
Tch	Channel Temperature	150	°C	
T _{STG}	Storage Temperature	-55 To 150	°C	

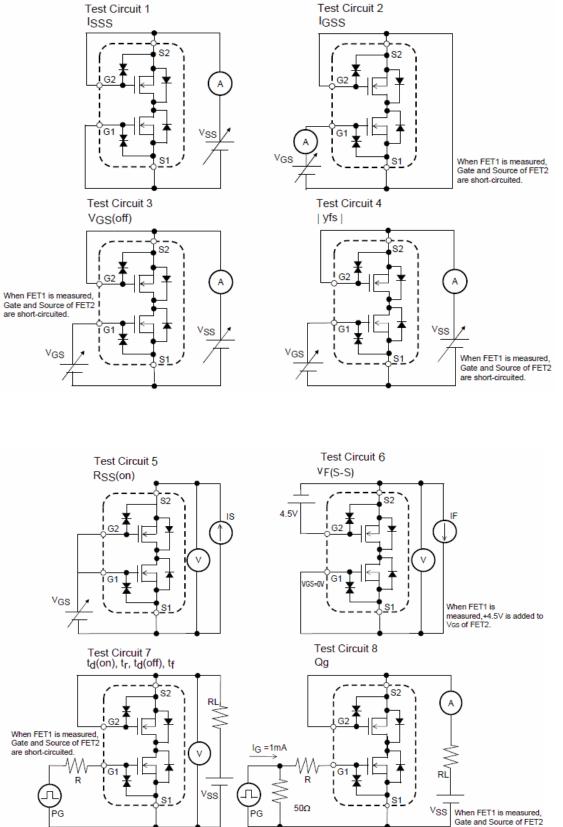


Electrical Characteristics (T_A=25 $^\circ\!\!\mathrm{C}$ unless otherwise noted)

Symbol	Parameter	Condition	Min	Тур	Max	Unit			
Static Parameters									
BV _{SSS}	Source to Source Breakdown Voltage	I _S =1mA, V _{GS} =0V, Test Circuit 1	20	-	-	V			
I _{SSS}	Zero- Gate Voltage Source Current	VSS=20V, VGS=0V, Test Circuit 1	-	-	1	μA			
I _{GSS}	Gate to Source Leakage Current	VSS=0V, VGS= ±8V, Test Circuit 2	-	-	±1	μA			
V _{GS(off)}	Cutoff Voltage	VSS=10V, I _S =1mA, Test Circuit 3	0.5	0.7	1.3	V			
yg _{FS}	Forward Transfer Admittance	V _{SS} =10V,I _S =3A, Test Circuit 4	6.5	-	-	S			
R _{SS(on)}	Static Source to Source On-Resistance	V _{GS} =4.5V,I _S =3A, Test Circuit 5		13.6	16	mΩ			
		V _{GS} =4.0V,I _S =3A, Test Circuit 5		14	18	mΩ			
		V _{GS} =3.7V,I _S =3A, Test Circuit 5		14.2	20	mΩ			
		V _{GS} =3.1V,I _S =3A, Test Circuit 5		15.1	23	mΩ			
		V _{GS} =2.5V,I _S =3A, Test Circuit 5		16.6	25	mΩ			
t _{d(on)}	Turn-on Delay Time		-	15	-	nS			
t _r	Turn-on Rise Time	V_{SS} =10V,I _S =3A V_{GS} =4.5V	-	50	-	nS			
t _{d(off)}	Turn-Off Delay Time	Test Circuit 7	-	40	-	nS			
t _f	Turn-Off Fall Time		-	55	-	nS			
Qg	Total Gate Charge	V _{SS} =10V,I _S =6A,V _{GS} =4.5V Test Circuit 8	-	25.4	-	nC			
V _{F(S-S)}	Diode Forward Voltage	V _{GS} =0V,I _S =6A	-	-	1.2	V			



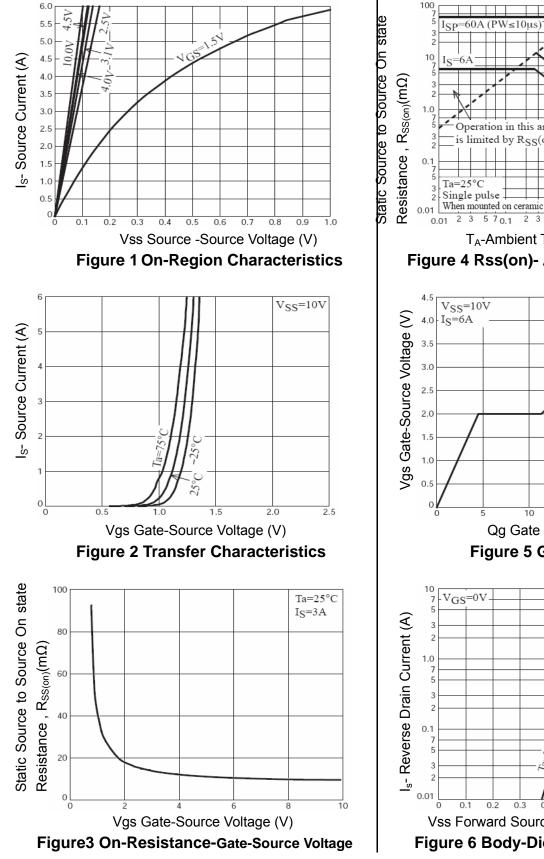
Test Circuit

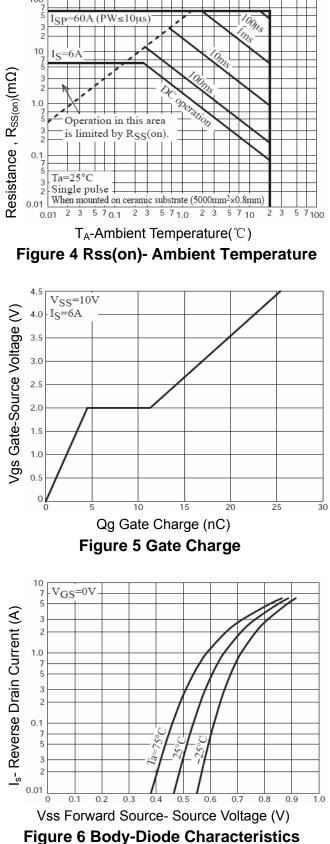


Gate and Source of FET are short-circuited.



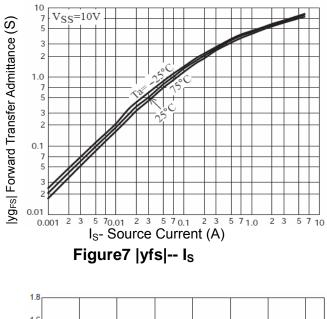
Typical Electrical and Thermal Characteristics (Curves)

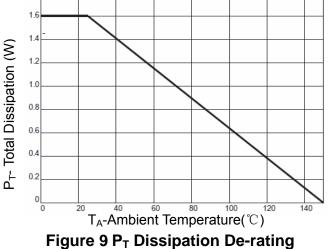


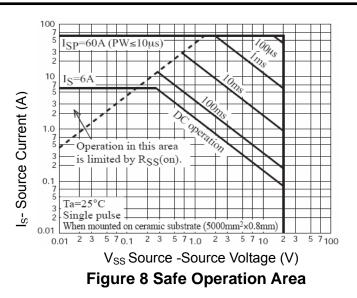




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